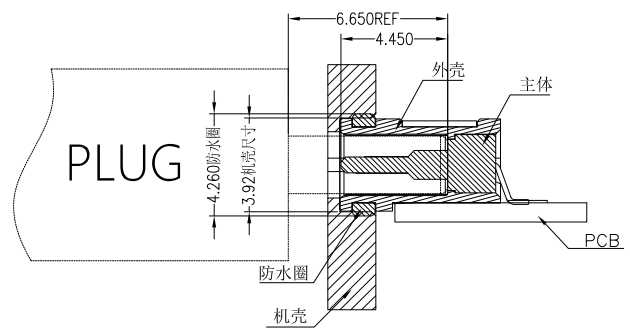
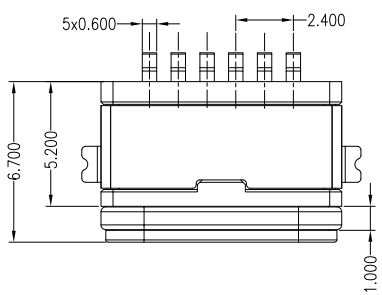
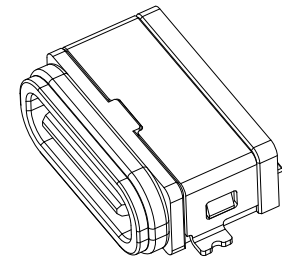


6	7	8		
ITEM	MODIFICATION	DATE	DRAW	APPROVE
△	新版发行	2021-06-26	望盛	袁俊林



防水原理：机壳压缩防水圈是其贴紧机壳，
（防水圈厚度4.26，压缩到3.92，四周单边压缩0.18）

产品防水机构示意图



Note:

1.Material:

1.1 Housing and sheath:High temperature thermoplastic UL94V-0
1.2 Contact:Copper Alloy
1.3 Shell:SUS
1.4 LATCH:SUS

2.ELECTRICAL:

2-1:CURUENT RATAING:
VBUS AND GND CONTACTS RATED AT 3A Max
VBUS AND GND CONTACTS RATED AT 0.5A Min
0.9Amps Max.for all other contact.
PARALLELED FOR A TOTAL OF 5A;

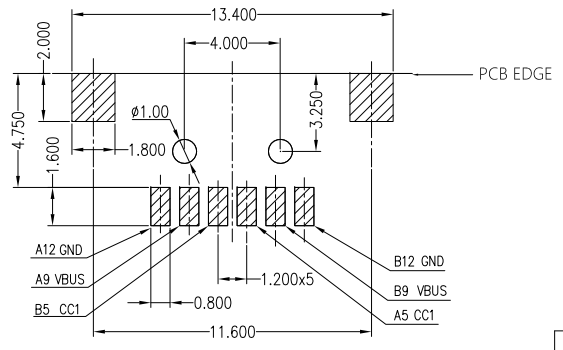
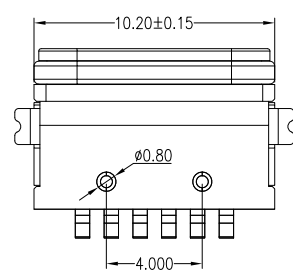
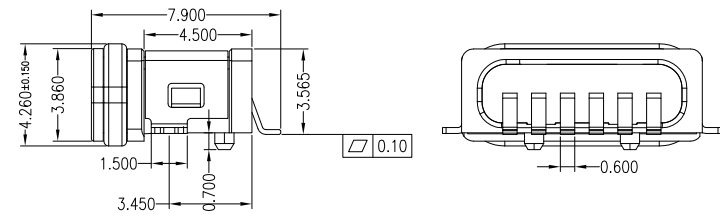
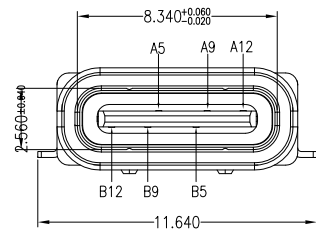
2-2:INITIAL CONTACT RESISTANCE:40 MILLIOHMS
2-3:DIELECTRIC WITHSTANDING VOLTAGE:100V AC MIN;

3:MECHANICAL CHARACTERISTICS:

3-1:MATING FORCE:5~20N
3-2:UNMATING FORCE:8~20N(INITIAL),6~20N(AFTER 10000 CYCLES)

3-3:FREQUENCE:200±50 CYCLES/HOUR,10000 CYCLES
3-4:OPERATING TEMPERATURE;-40°~80°.

4:WATERPROOF:IP-X8.
CX008



PCB LAYOUT 图仅供参考

5	OUT SHELL	PA46 BLACK
4	HOUSING	LCP BLACK
3	RING	RED Silica Gel
2	Shell	SUS Ni80a"
1	Contact	C7025 AuNi1U"
ITEM	DEFINITION	SPEC DESCRIPTION

TABLE B

A5	CC1	B12	GND	.X±0.15	Ang,±1°
A9	VBUS	B9	VBUS	.XX±0.10	
A12	GND	B5	CC2	.XXX±0.05	
PIN	SIGNAL NAME	PIN	SIGNAL NAME		

PROJ.	东莞市超讯电子有限公司 transcend communication		
DIMENSION STYLE MM ONLY			
DESIGN UNITY METRIC	DRAWN BY 望盛	DATE 2021-06-26	TITLE TYPE C 6PIN SMT 半包防水型母座(外壳 SMT)
	CHECKED BY 望盛	DATE 2021-06-26	PART NO. BNF01S2208R-W
SCALE 1:1	APPROVED BY 袁俊林	DATE 2021-06-26	MOLD NO. DWG-USB CF-069
			SHEET NO. 1 OF 1
			C REV. A0